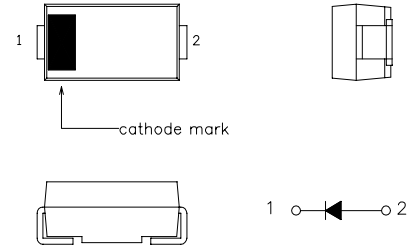


# SBD Type : EC10QS03L

## FEATURES

- \* Miniature Size, Surface Mount Device
- \* Extremely Low Forward Voltage Drop
- \* Low Power Loss, High Efficiency
- \* High Surge Capability
- \* 30 Volts through 100Volts Types Available
- \* Packaged in 12mm Tape and Reel
- \* Not Rolling During Assembly

## OUTLINE DRAWING



## Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10QS03L			Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	30			V
Average Rectified Output Current	$I_O$	1.0	$T_a=28\text{ }^\circ\text{C}$ *1	50Hz Half Sine Wave Resistive Load	A
		1.0	$T_a=58\text{ }^\circ\text{C}$ *2		
RMS Forward Current	$I_{F(RMS)}$	1.57			A
Surge Forward Current	$I_{FSM}$	20	50Hz Half Sine Wave, 1cycle Non-repetitive		A
Operating Junction Temperature Range	$T_{jw}$	-40 to +150			$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	-40 to +150			$^\circ\text{C}$

## Electrical • Thermal Characteristics

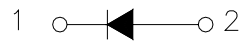
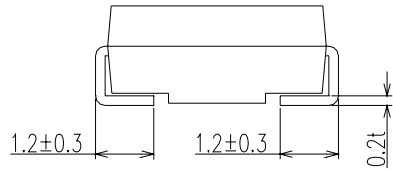
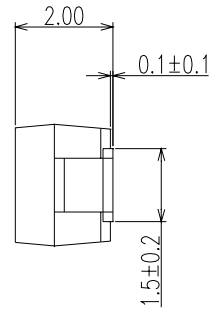
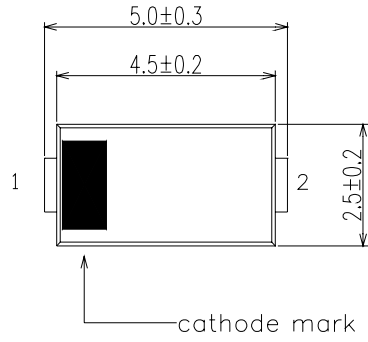
Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	$I_{RM}$	$T_j= 25^\circ\text{C}$ , $V_{RM}= V_{RRM}$	-	-	1.0	mA	
Peak Forward Voltage	$V_{FM}$	$T_j= 25^\circ\text{C}$ , $I_{FM}= 1.0\text{A}$	-	-	0.45	V	
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	157	$^\circ\text{C}/\text{W}$
			*2	-	-	108	

\*1 Glass Epoxy Substrate Mounted

\*2 Alumina Substrate Mounted

Soldering Lands=2x2mm, Both Sides

EC10QS03L OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

